15. The camera or optical module according to any one of the previous claims, wherein the interior space is hermetically sealed from an outside.

16. The camera or optical module according to any one of the previous claims, wherein the screen device or screen comprises at least one screening wall ranging from an image-side surface of the first substrate to an object-side surface of the second substrate.

17. A method of manufacturing, on a wafer scale, a plurality of cameras comprising the steps of:

- providing a first substrate wafer, a second substrate wafer and a spacer wafer with a plurality of through holes,
- bringing, in arbitrary sequence the spacer wafer in contact with one of the first and of the second substrate wafer with a first portion of an adhesive in-between and introducing a screen device in at least one of the through holes,
- thereafter bringing the second one of first and of the second substrate wafer and the spacer wafer in contact with each other with a second portion of an adhesive in-between,
- hardening the second portion of the adhesive, and
- dividing the resulting assembly into a plurality of camera-scale devices;

wherein the screen device is not a coating layer on the first and/or second substrate or on the spacer.

~~18. The method according to claim 17, wherein the screen device is not a coating layer on the first and/or second substrate or on the spacer.~~